

Title (en)

Interface preparation for weld joints

Title (de)

Zwischenschichtvorbereitung für geschweisste Verbindungsstelle

Title (fr)

Interface préparatoire pour joints soudés

Publication

EP 1291115 A3 20041117 (EN)

Application

EP 02077825 A 20020715

Priority

US 94188001 A 20010829

Abstract (en)

[origin: EP1291115A2] The present invention provides a structural assembly comprising a first workpiece and a second workpiece. The second workpiece (12b) at least partially underlies the first workpiece (12a) so as to define an interface therebetween. The assembly includes a friction stir weld joint joining the first and second workpieces. The assembly also includes an interface layer (16) positioned between the first and second workpieces. The interface layer comprises a material having a melting temperature lower than the solidus temperatures of the first and second workpieces. The interface layer at least partially fills the interface proximate to the friction stir weld joint to thereby increase the strength and fracture toughness of the weld joint, as well as other mechanical and chemical properties, including resistance to crack growth and corrosion resistance. <IMAGE>

IPC 1-7

B23K 20/12

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CPC (source: EP US)

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Citation (search report)

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